



News Release



Unisem Ipoh and UAT receive SEMCO award for Best Semiconductor Quality Cooperation

Ipoh, Malaysia, February 2018 – This past February, Unisem received an Award from the Module Quality Innovation Team of their key customer Samsung Electro Mechanics. The award was presented by JeongYo Jeong, SEMCO Quality Group Leader and accepted by Unisem Group COO HL Lee and Unisem Ipoh COO CS Ho. The award was given in appreciation of Unisem’s full support towards customer quality, exhibiting outstanding yields and successfully implementing their quality improvement projects.

Samsung Electro-Mechanics is a world leader in each of its key business segments including boards, chip parts, camera modules, and communication modules.

About Unisem

Unisem is a global provider of semiconductor assembly and test (OSAT) services for many of the world's most successful electronics companies. We offer an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding; a wide range of leadframe and substrate IC packaging; wafer level CSP; and RF, analog, digital, and mixed signal test. Our turnkey services include design, assembly, test, failure analysis, and electrical, mechanical, and thermal characterization and modeling. The company has factory locations in Ipoh, Malaysia; Chengdu, People's Republic of China and Batam, Indonesia. Unisem is headquartered in Kuala Lumpur, Malaysia.

For additional information on Unisem, please visit: www.unisemgroup.com.

Contact:

Chris Stai, 209-534-6398

MarCom Manager

cstai@unisemgroup.com